

8-lead Micro Leadframe Package (MLP) 2x3 for low voltage EEPROM

Extremely compact, yet incredibly dense



Innovative solution for EEPROM

New ultra thin, fine-pitch, dual flat 2x3mm MLP package combines significant improvements in terms of space saving and footprint compatibility. The 8-pin MLP8 2x3 is the smallest in the world. Associated with state-of-the-art advanced EEPROM technology, it provides the best innovative solution for low voltage parameter storage applications. **STMicroelectronics'** new MLP-packaged devices allow entry into tightly spaced applications that were previously not attainable.

Take the lead for all nomadic applications with the new, thin, compact, lead-free package

Specially tailored for advanced EEPROM technology, this 8-lead UFDFPN8 (ultra thin, fine-pitch, dual flat, no-lead) package has a body width of 2mm and a length of 3mm. Its 0.6mm height represents a real advantage for designers, and makes it an ideal choice for applications seriously constrained by space, especially portable device applications including:

- Computer: printers, hard disk drive, wireless mice
- Communications: mobile phones, peripherals like headsets, cordless phones accessories, Wi-Fi, Bluetooth, WLAN
- Consumer: LCD drivers, PDAs, MP3s, digital cameras, games and cartridges, camcorders, mobile power supply
- Automotive: remote keyless entry, car radio, navigation
- Medical: hearing aids, blood sugar analysis

The smallest package combined with low voltage advanced EEPROM

Offered for EEPROM in 1.8V, the MLP8 2x3 uses ST's ECOPACK® lead-free technology for RoHS compliance (the EU Directive on the restriction on use of hazardous substances). Delivered in standard tape-and-reel, this tiny robust package is easy to handle in automated production lines, and with a 0.5mm lead pitch, the package is also easy to mount.

Low cost – which is a driving force for these markets – is another benefit of this package.

MLP8 2X3 features

- Typical values:
 - Body width: 2mm
 - Body length: 3mm
 - Thin: 0.55mm
 - Pitch: 0.5mm
- ST ECOPACK lead-free, RoHS-compliant



(package not to scale)

Low voltage serial EEPROM – MLP8 (2x3) portfolio

| Serial EEPROM – I ² C | | | |
|---|------|-----------------|-------------------|
| Part number | Size | V _{cc} | Temperature range |
| M24C02-RMB6G | 2Kb | 1.8V-5.5V | -40 to +85°C |
| M24C04-RMB6G | 4Kb | 1.8V-5.5V | -40 to +85°C |
| M24C08-RMB6G | 8Kb | 1.8V-5.5V | -40 to +85°C |
| M24C16-RMB6G | 16Kb | 1.8V-5.5V | -40 to +85°C |
| M24C32-RMB6G | 32Kb | 1.8V-5.5V | -40 to +85°C |
| M24C32-FMB5G | 32Kb | 1.7V-5.5V | -20 to +85°C |
| M24C64-RMB6G* | 64Kb | 1.8V-5.5V | -40 to +85°C |
| Serial EEPROM – SPI | | | |
| M95020-RMB6G | 2Kb | 1.8V-5.5V | -40 to +85°C |
| M95040-RMB6G | 4Kb | 1.8V-5.5V | -40 to +85°C |
| M95080-RMB6G | 8Kb | 1.8V-5.5V | -40 to +85°C |
| M95160-RMB6G | 16Kb | 1.8V-5.5V | -40 to +85°C |
| M95320-RMB6G | 32Kb | 1.8V-5.5V | -40 to +85°C |
| M95640-RMB6G | 64Kb | 1.8V-5.5V | -40 to +85°C |
| Serial EEPROM – Microwire | | | |
| M93C66-RMB6TG | 4Kb | 1.8V-5.5V | -40 to +45°C |
| Serial EEPROM for DIMM serial presence detect | | | |
| M34C02-RMB6G | 2Kb | 1.8V-5.5V | -40 to +85°C |
| M34E02-FMB1G | 2Kb | 1.7V-3.6V | 0 to +70°C |

* Under development



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